



## Materials Declaration Form

<b>IPC Form Type *</b>	<b>1752 Distribute</b>	<b>Version</b>	<b>2</b>
<b>Sectionals *</b>	<b>Material Info Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>
<b>* : Required Field</b>			

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2015-02-24</b>
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	<b>Emilio Castelli</b>	<b>Representative Title</b>	<b>APG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/online_tech_support.html">http://www.st.com/web/en/support/online_tech_support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	<b>true</b>	<b>Legal Declaration *</b>	<b>Standard</b>
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L9663	BA3Q*UAJ3BAP	A	ZY1A	2015-02-24
Amount		UoM	Unit type	ST ECOPACK Grade
70.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	7x7x1.0	32	flat	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-16th June 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BA3Q*UAJ3BAP					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.872	mg	supplier	die	Silicon (Si)	7440-21-3		4.119	mg	845443	58843
Die				supplier	metallization	Aluminium (Al)	7429-90-5		0.015	mg	3079	214
Die				supplier	metallization	Copper (Cu)	7440-50-8		0.395	mg	81076	5643
Die				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	205	14
Die				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	616	43
Die				supplier	metallization	Tungsten (W)	7440-33-7		0.023	mg	4721	329
Die				supplier	metallization	Nickel (Ni)	7440-02-0		0.049	mg	10057	700
Die				supplier	metallization	Platinum (Pt)	7440-06-4		0.027	mg	5542	386
Die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.098	mg	20115	1400
Die				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.004	mg	821	57
Die				supplier	back side metallization	Gold (Au)	7440-57-5		0.010	mg	2053	143
Die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.028	mg	5747	400
Die				supplier	back side metallization	Vanadium (V)	7440-62-2		0.002	mg	411	29
Die				supplier	glass coating	Glass: Silicon Dioxide (SiO2)	7631-86-9		0.098	mg	20115	1400
LEADFRAME (MHT- C194 Ag)	Copper and its alloy	24.553	mg	supplier	ALLOY	Copper (Cu)	7440-50-8		22.535	mg	917810	321929
LEADFRAME (MHT- C194 Ag)				supplier	ALLOY	Iron (Fe)	7439-89-6		0.543	mg	22115	7757
LEADFRAME (MHT- C194 Ag)				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.028	mg	1140	400
LEADFRAME (MHT- C194 Ag)				supplier	ALLOY	Phosphorus (P)	7723-14-0		0.007	mg	285	100
LEADFRAME (MHT- C194 Ag)				supplier	COATING	Silver(Ag)	7440-22-4		1.440	mg	58649	20571
DIE ATTACH (Henkel - 3230)	Other organic materials	1.099	mg	supplier	GLUE	Epoxy resin	Trade secret		0.220	mg	200182	3143
DIE ATTACH (Henkel - 3230)				supplier	GLUE	Silver(Ag)	7440-22-4		0.769	mg	699727	10986
DIE ATTACH (Henkel - 3230)				supplier	GLUE	Anhydride	26544-38-7		0.110	mg	100091	1571
BONDING WIRE (Heesung - PCC wire)	Other inorganic materials	1.597	mg	supplier	BONDING WIRE	Copper (Cu)	7440-50-8		1.596	mg	999374	22800
BONDING WIRE (Heesung - PCC wire)				supplier	BONDING WIRE	Palladium (Cu)	7440-05-3		0.001	mg	626	14
ENCAPSULATION (Sumitomo -G700Y)	Other inorganic materials	35.416	mg	supplier	MOLDING COMPOUND	Epoxy Resin	Trade secret		3.188	mg	90016	45543
ENCAPSULATION (Sumitomo -G700Y)				supplier	MOLDING COMPOUND	Silica fused (SiO2)	60676-86-0		30.457	mg	859979	435100
ENCAPSULATION (Sumitomo -G700Y)				supplier	MOLDING COMPOUND	Phenol Resin	Trade secret		1.594	mg	45008	22771
ENCAPSULATION (Sumitomo -G700Y)				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		0.177	mg	4998	2529
FINISHING- (ST380 -Sn)	Other inorganic materials	2.547	mg	supplier	CONNECTION COATING	Tin (Sn)	7440-31-5		2.547	mg	1000000	36386